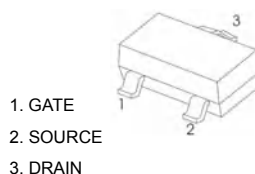


Features

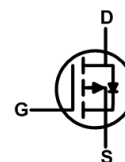
- As complementary type, the NPN transistor MMBT3904 is Recommended
- Epitaxial planar die construction



SOT-23



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

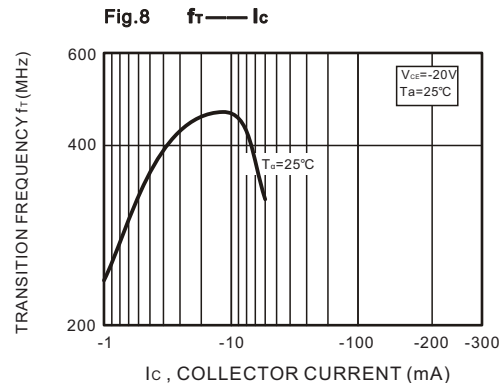
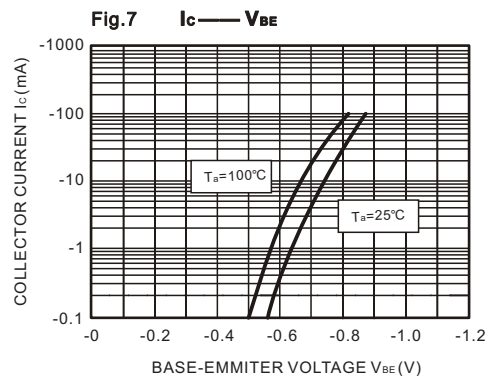
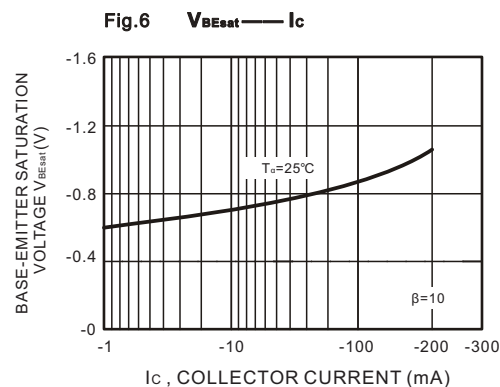
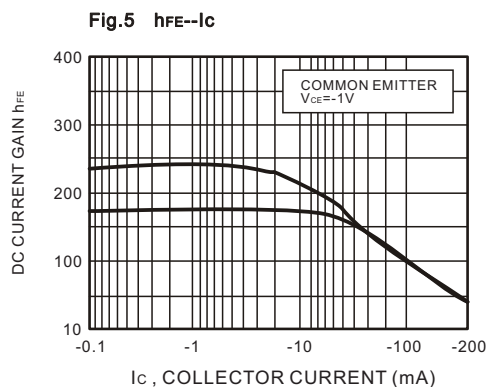
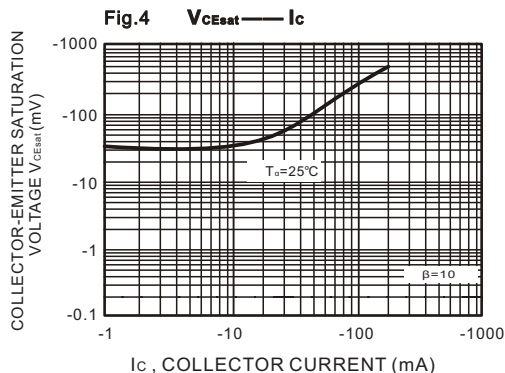
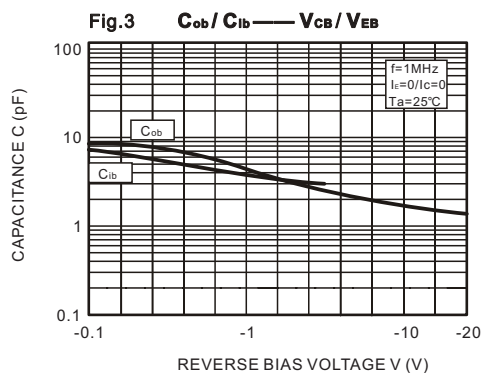
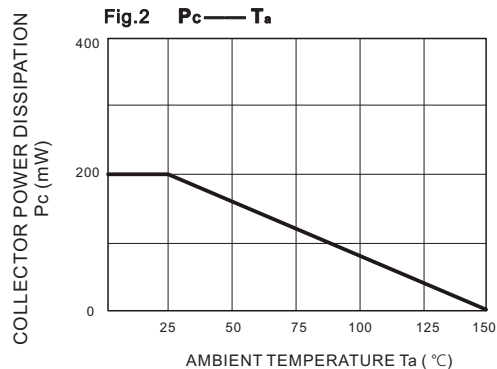
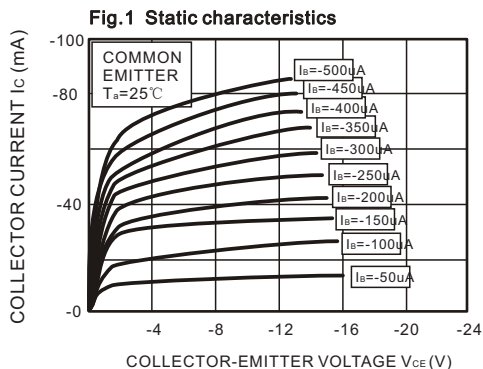
Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Collector–Base Voltage	V_{CBO}	-40	V
Collector–Emitter Voltage	V_{CEO}	-40	V
Emitter–Base Voltage	V_{EBO}	-5	V
Collector Current — Continuous	I_C	-0.2	A
Collector Dissipation	P_C	0.2	W
Thermal Resistance From Junction To Ambient	R_{thJA}	625	°C/W
Operation Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	°C

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

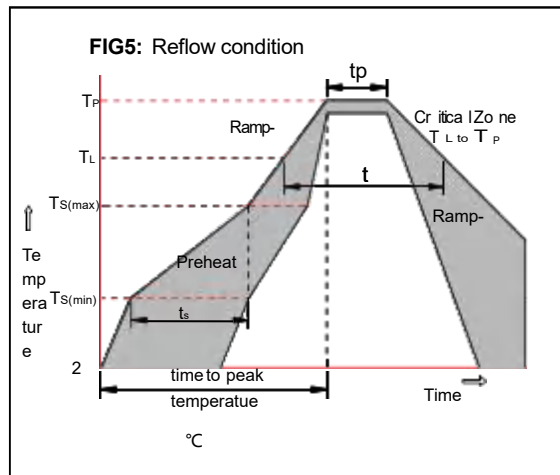
Parameter	Symbol	Test conditions	Min	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C = -10\mu\text{A}, I_E = 0$	-40		V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	$I_C = -1\text{ mA}, I_B = 0$	-40		V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E = -10\mu\text{A}, I_C = 0$	-5		V
Collector cut-off current	I_{CBO}	$V_{CB} = -40\text{V}, I_E = 0$		-100	nA
Collector cut-off current	I_{CEX}	$V_{CE} = -30\text{V}, V_{CE} = -3\text{V}$		-50	nA
Emitter cut-off current	I_{EBO}	$V_{EB} = -5\text{V}, I_C = 0$		-100	nA
DC current gain	h_{FE1}	$V_{CE} = -1\text{V}, I_C = -10\text{mA}$	100	300	
	h_{FE2}	$V_{CE} = -1\text{V}, I_C = -50\text{mA}$	60		
	h_{FE3}	$V_{CE} = -2\text{V}, I_C = -100\text{mA}$	30		
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -50\text{mA}, I_B = -5\text{mA}$		-0.3	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = -50\text{mA}, I_B = -5\text{mA}$		-0.95	V
Transition frequency	f_T	$V_{CE} = -20\text{V}, I_C = -10\text{mA}, f = 100\text{MHz}$	300		MHZ
Delay time	t_d	$V_{CC} = -3\text{V}, V_{BE} = -0.5\text{V}$ $I_C = -10\text{mA}, I_{B1} = I_{B2} = -1\text{mA}$		35	ns
Rise time	t_r			35	ns
Storage time	t_s	$V_{CC} = -3\text{V}, I_C = -10\text{mA}$ $I_{B1} = I_{B2} = -1\text{mA}$		225	ns
Fall time	t_f			75	ns

RATING AND CHARACTERISTIC CURVES



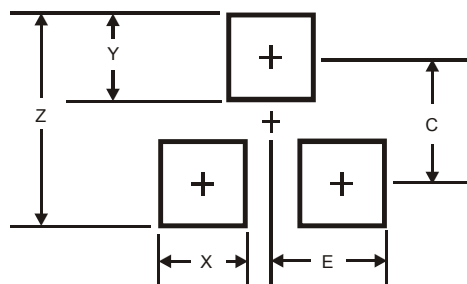
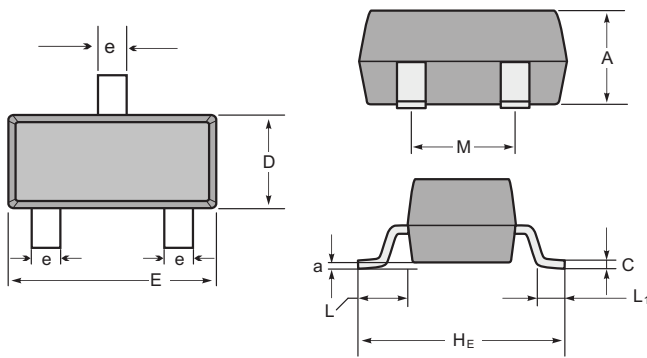
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

SOT23

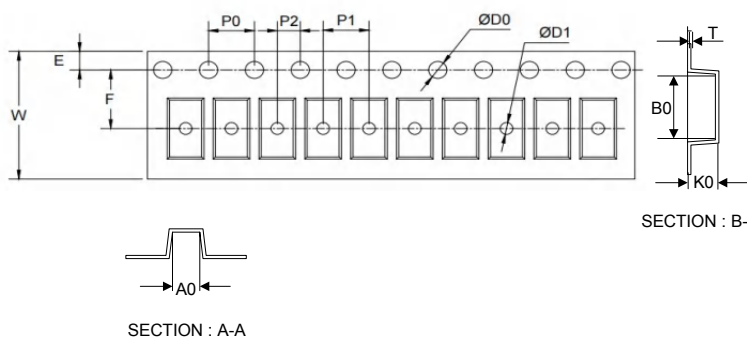
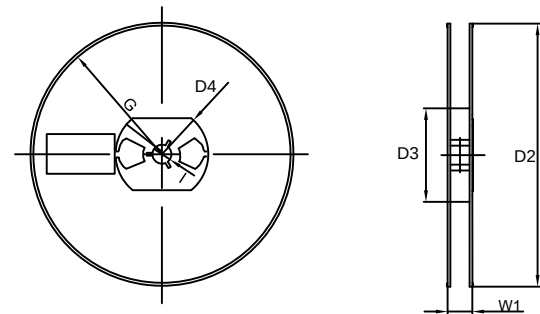


SOT-23 mechanical data

UNIT		A	C	D	E	H _E	e	M	L	L ₁	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

Tape & reel specification

Tape		Symbol	Dimension (mm)
 SECTION : A-A SECTION : B-B		P0	4.00±0.10
		P1	4.00±0.10
		P2	2.00±0.10
		D0	1.55±0.10
		D1	1.05±0.10
		E	1.55±0.10
		F	3.60±0.10
		W	8.00±0.10
		A0	3.80±0.20
		B0	3.25±0.20
		K0	1.45±0.10
		T	0.25±0.05
		D2	178.0±3.0
		D3	55Min.
		D4	R24.0±3.0
7" Reel		G	R82.0±3.0
		I	13.0±2.0
		W1	11.0±3.0
		Quantity: 3000PCS	